

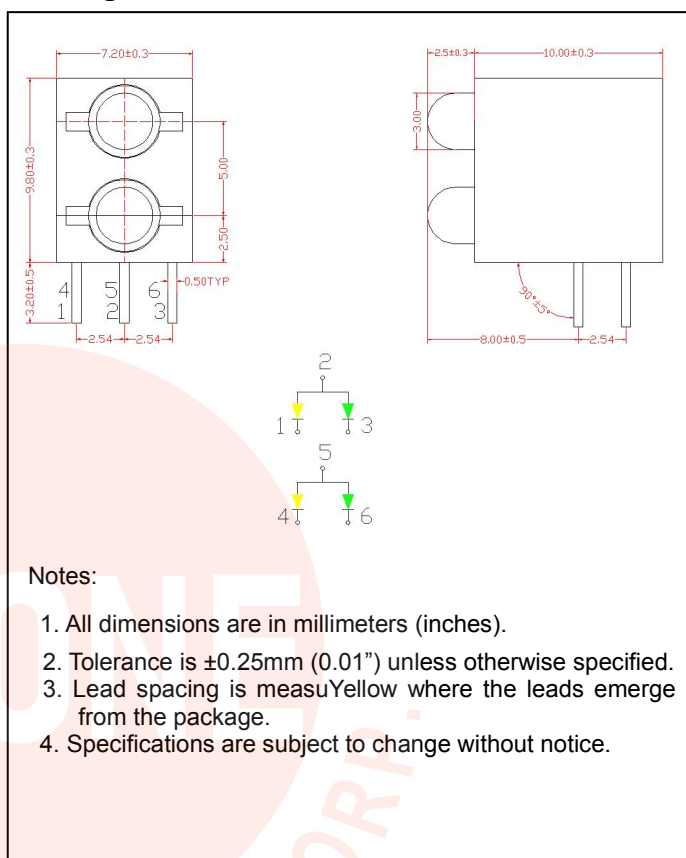
● Features:

1. Chip material:AlGaInp / AlGaInp
(Yellow / Green)
2. Emitted color : Yellow and Green
3. Lens Appearance : White Diffused
4. Designed for ease in circuit board assembly.
5. Black case enhance contrast ratio.
6. Solid state light source.
7. Reliable and rugged.
8. 3mm diameter package.
9. This product don't contained restriction substance, compliance ROHS standard.

● **Applications:**

1. TV set
2. Monitor
3. Telephone
4. Computer
5. Circuit board

● Package dimensions



● **Absolute Maximum Ratings**(Ta=25°C)

Parameter	Symbol	Yellow	Green	Unit
Power Dissipation	Pd	70	70	mW
Forward Current	I _F	30	30	mA
Peak Forward Current*1	I _{FP}	100	100	mA
Reverse Voltage	V _R	5		V
Operating Temperature	Topr	-40℃~80℃		
Storage Temperature	Tstg	-40℃~85℃		
Soldering Temperature	Tsol	260℃ (for 5 seconds)		

*1Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width.

● **Electrical and optical characteristics(Ta=25°C)**

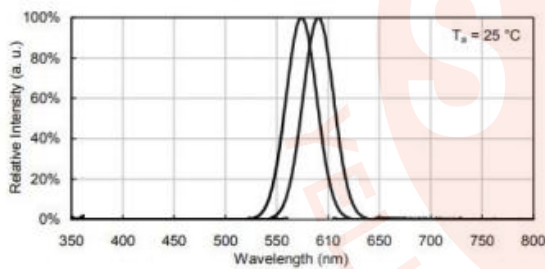
Parameter	Symbol	Condition	Color	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F=20\text{mA}$	Yellow Green	1.8 1.8	- -	2.4 2.4	V
Luminous Intensity	I_v	$I_F=20\text{mA}$	Yellow Green	40 15	80 30	160 60	mcd
Reverse Current	I_R	$V_R=5\text{V}$	Yellow Green	- -	588 569	5 5	μA
Dominant Wave Length	λ_d	$I_F=20\text{mA}$	Yellow Green	586 566	590 570	594 574	nm
Spectral Line Half-width	$\Delta\lambda$	$I_F=20\text{mA}$	Yellow Green	- -	30 30	- -	nm
Viewing Angle	$2\theta_{1/2}$	$I_F=20\text{mA}$	Yellow Green	- -	80 80	- -	deg

● **Typical Electro-Optical Characteristics Curves**

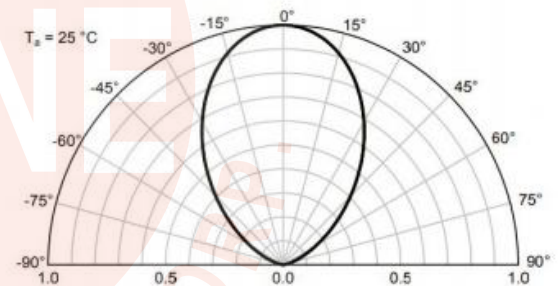
Yellow and Green

TECHNICAL DATA

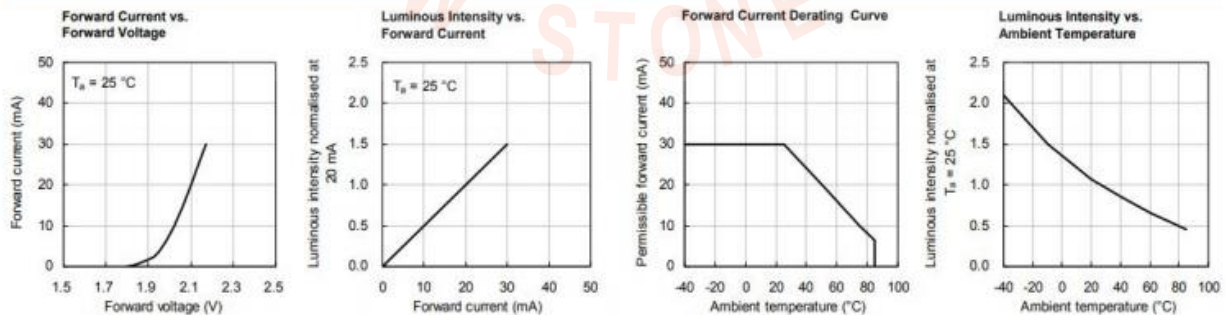
RELATIVE INTENSITY vs. WAVELENGTH



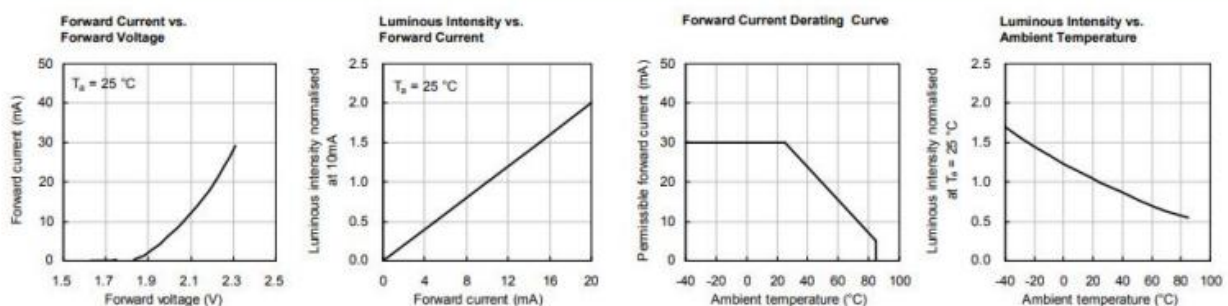
SPATIAL DISTRIBUTION



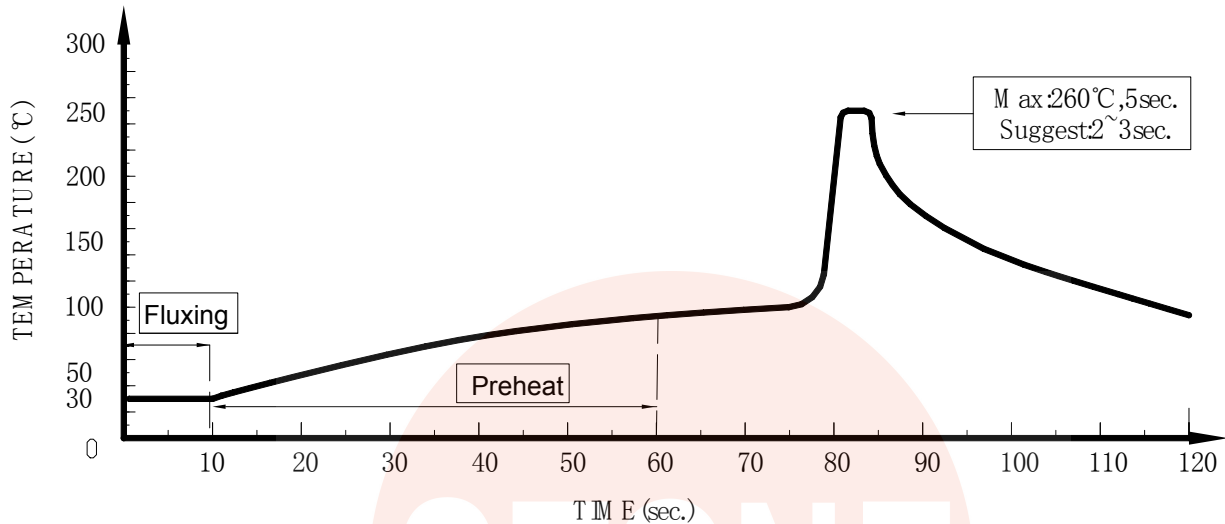
GREEN



Yellow



●Dip Soldering



1. Please avoid any external stress applied to the lead-frames and epoxy while the LEDs are at high temperature, especially during soldering
2. DIP soldering and hand soldering should not be done more than one time.
3. After soldering, avoid the epoxy lens from mechanical shock or vibration until the LEDs are back to room temperature.
4. Avoid rapid cooling during temperature ramp-down process
5. Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs

●IRON Soldering

A : Max : 350°C Within 3 sec. One time only.

B : The products of 3mm without flange, welding condition of flat plate PCB Max : 350°C Within 2 sec. One time only

